

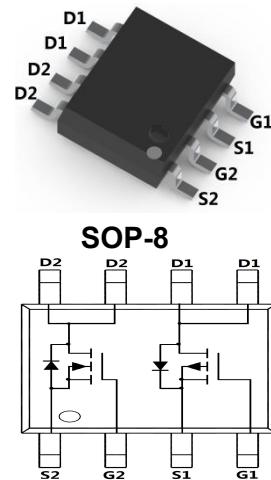
COMPLEMENTARY MOSFET

FEATURES

- $V_{DS}=30V, I_D=7.2A, R_{DS(ON)}\leq 24m\Omega @ V_{GS}=10V$
- $V_{DS}=-30V, I_D=-5.3A, R_{DS(ON)}\leq 32m\Omega @ V_{GS}=-10V$
- Low gate charge and Ultra low on-resistance
- For low Input Voltage inverter applications
- Surface Mount device

MECHANICAL DATA

- Case: SOP-8
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Weight: 0.3 grams (approximate)


MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Max N-channel	Max P-channel	Unit
Drain-source voltage	V_{DS}	30	-30	V
Gate-source voltage	V_{GS}	± 20	± 20	V
Continuous drain current	I_D	7.2	-5.3	A
		6.2	-4.5	A
Pulsed drain current	I_{DM}	64	-40	A
Avalanche current	I_{AS}, I_{AR}	9	17	A
Avalanche energy L=0.1mH	E_{AS}, E_{AR}	12	43	mJ
Power dissipation	P_D	2	2	W
		1.44	1.44	W
Thermal resistance from Junction to ambient	$R_{\theta JA}$	100		$^\circ C/W$
Thermal resistance from Junction to Lead	$R_{\theta JL}$	40		$^\circ C/W$
Junction temperature	T_J	150		$^\circ C$
Storage temperature	T_{STG}	-55 ~ +150		$^\circ C$

N-CHANNEL ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Drain-Source breakdown voltage	$V_{(BR)DSS}^*$	30			V	$V_{GS}=0V, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}^*			1	μA	$V_{DS}=30V, V_{GS}=0V$
Gate-body leakage current	I_{GSS}^*			± 100	nA	$V_{DS}=0V, V_{GS}=\pm 20V$
Gate-threshold voltage	$V_{GS(th)}^*$	1.5	2.1	2.6	V	$V_{DS}=V_{GS}, I_D=250\mu A$
On-State Drain Current	$I_{D(ON)}$	64			A	$V_{DS}=5V, V_{GS}=10V$
Drain-source on-resistance	$R_{DS(ON)}^*$		17.7	24	$m\Omega$	$V_{GS}=10V, I_D=7.2A$
			23.5	29	$m\Omega$	$V_{GS}=10V, I_D=7.2A, T_J=125^\circ C$
			21	27	$m\Omega$	$V_{GS}=4.5V, I_D=5A$
Forward transconductance	g_{FS}		20		S	$V_{DS}=5V, I_D=7.2A$
Diode forward voltage	V_{SD}		0.74	1	V	$I_S=1A, V_{GS}=0V$
Diode forward current	I_S			2.5	A	
Pulsed Body-Diode Current	I_{SM}			64	A	
Input capacitance	C_{iss}	373	448		pF	$V_{DS}=15V, V_{GS}=0V, f=1MHz$
Output capacitance	C_{oss}	67			pF	
Reverse transfer capacitance	C_{rss}	41			pF	
Gate resistance	R_a	1.8	2.8		Ω	$V_{DS}=0V, V_{GS}=0V, f=1MHz$
Total gate charge	Q_g		3.5		nC	$V_{GS}=4.5V, V_{DS}=15V, I_D=7.2A$
Total gate charge			7.2	11	nC	
Gate-source charge	Q_{gs}	1.3			nC	$V_{GS}=10V, V_{DS}=15V, I_D=7.2A$
Gate-drain charge	Q_{gd}	1.7			nC	
Turn-on delay time	$t_{d(on)}$	4.5			nS	$V_{GS}=10V, V_{DS}=15V, R_{GEN}=3\Omega, R_L=2.1\Omega$
Turn-on rise time	t_r	2.7			nS	
Turn-off delay time	$t_{d(off)}$	14.9			nS	
Turn-off fall time	t_f	2.9			nS	
Body Diode Reverse Recovery Time	t_{rr}	10.5	12.6		nS	$I_F=7.2A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}		4.5		nC	$I_F=7.2A, dI/dt=100A/\mu s$

*Pulse test ; Pulse width $\leq 300\mu s$, Duty cycle $\leq 0.5\%$.

COMPLEMENTARY MOSFET

N-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

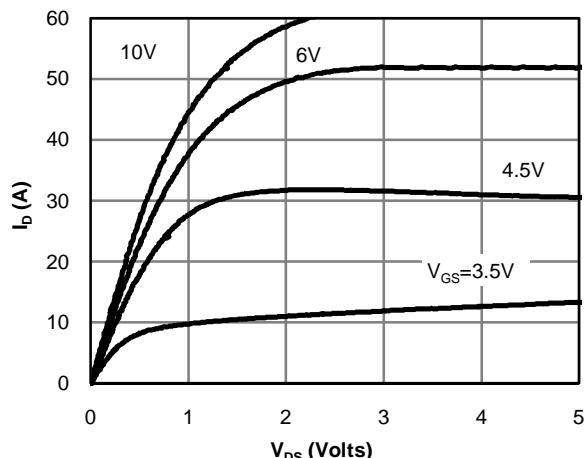


Fig 1: On-Region Characteristics

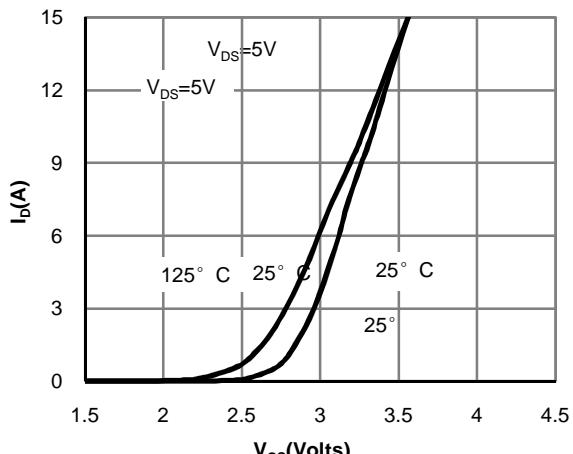


Figure 2: Transfer Characteristics

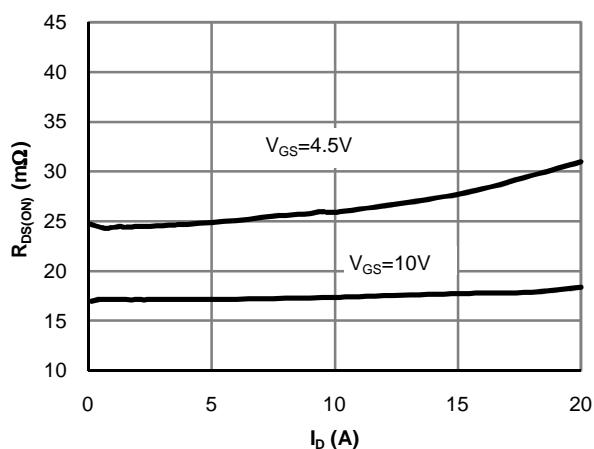


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

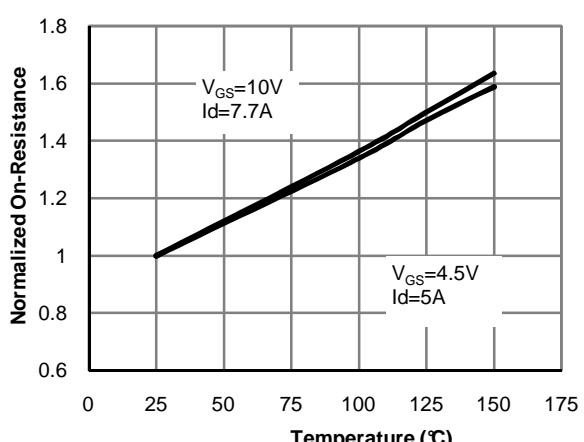


Figure 4: On-Resistance vs. Junction Temperature

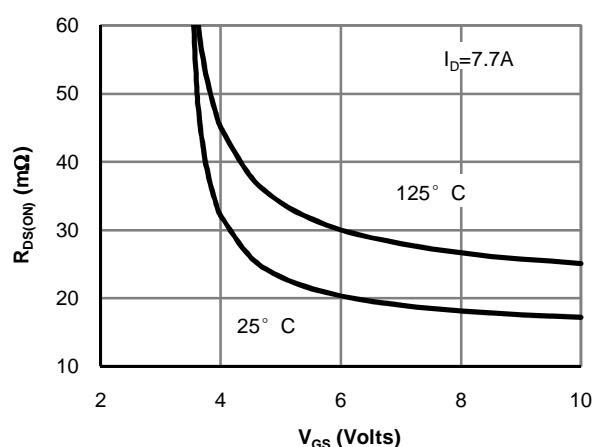


Figure 5: On-Resistance vs. Gate-Source Voltage

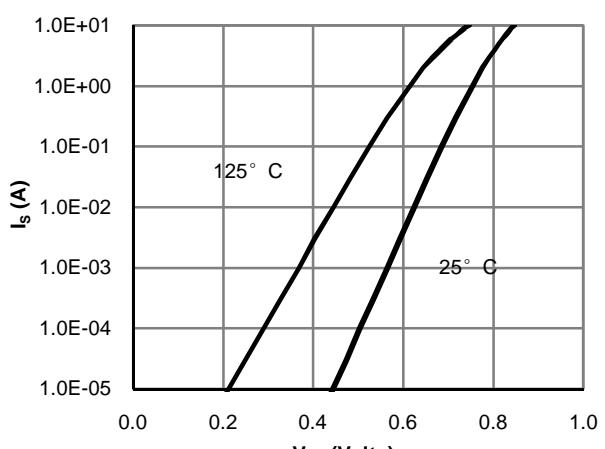


Figure 6: Body-Diode Characteristics

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N-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

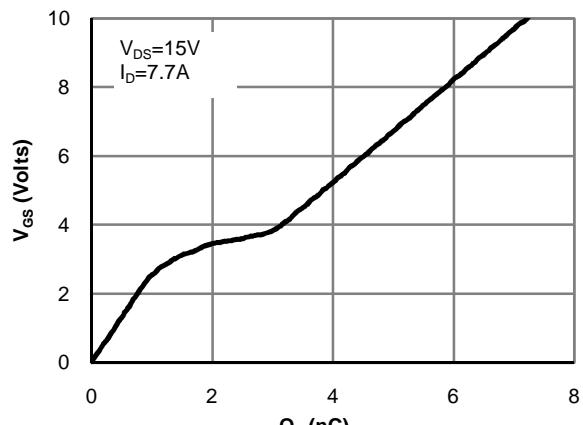


Figure 7: Gate-Charge Characteristics

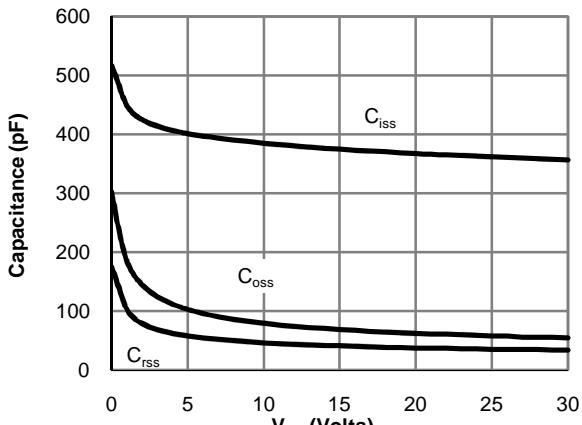


Figure 8: Capacitance Characteristics

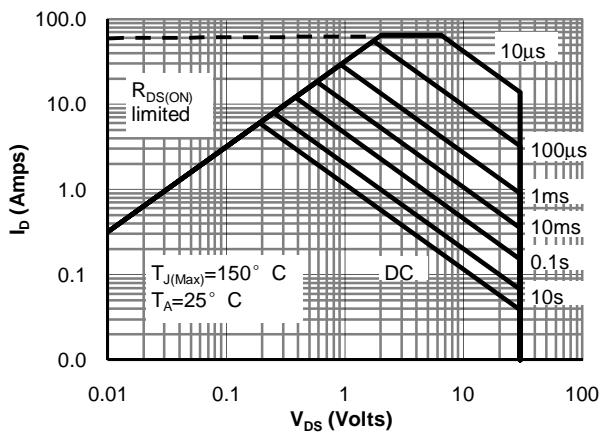


Figure 9: Maximum Forward Biased Safe Operating Area

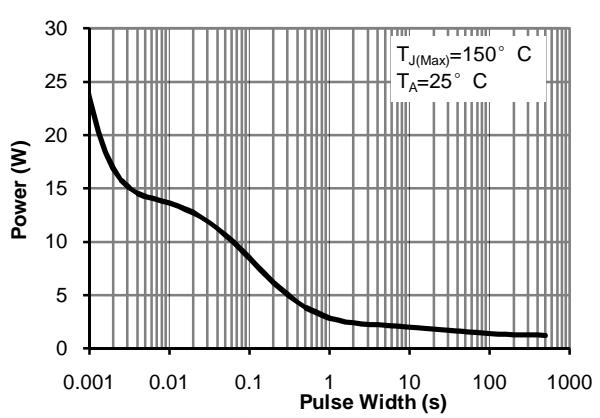


Figure 10: Single Pulse Power Rating Junction-to-Ambient

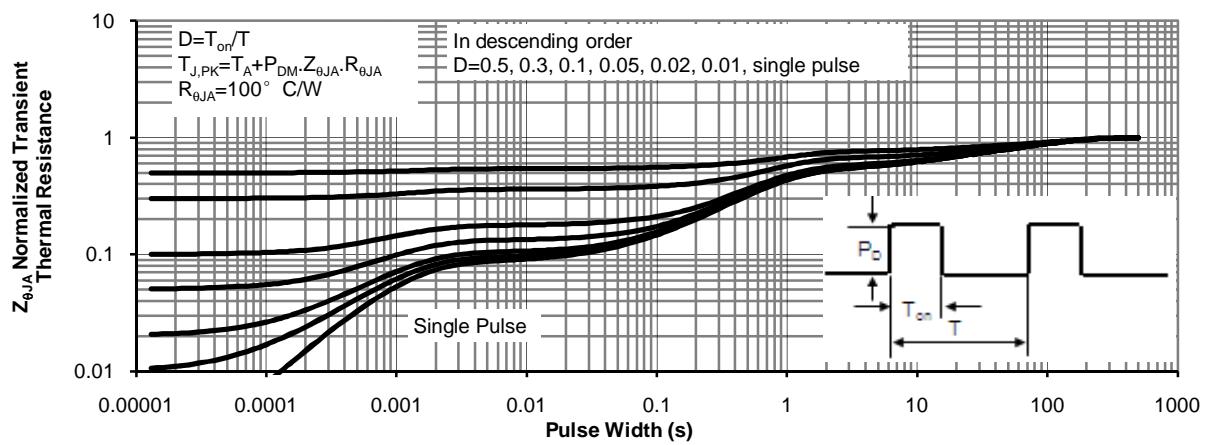


Figure 11: Normalized Maximum Transient Thermal Impedance

COMPLEMENTARY MOSFET
P-CHANNEL ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Drain-Source breakdown voltage	V _{(BR)DSS} *	-30			V	V _{GS} =0V, I _D =-250μA
Zero gate voltage drain current	I _{DSS} *			-1	μA	V _{DS} =-30V, V _{GS} =0V
Gate-body leakage current	I _{GSS} *			±100	nA	V _{DS} =0V, V _{GS} =±20V
Gate-threshold voltage	V _{GS(th)} *	-1.3	-1.85	-2.4	V	V _{DS} =V _{GS} , I _D =-250μA
On-State Drain Current	I _{D(ON)} *	-40			A	V _{DS} =-5V, V _{GS} =-10V
Drain-source on-resistance	R _{DS(ON)} *		23	32	mΩ	V _{GS} =-10V, I _D =-5.3A
			31.5		mΩ	V _{GS} =-10V, I _D =-5.3A, T _J =125°C
			33	55	mΩ	V _{GS} =-4.5V, I _D =-4.5A
Forward transconductance	G _{FS}		19		S	V _{DS} =-5V, I _D =-5.3A
Diode forward voltage	V _{SD}		-0.8	-1	V	I _S =-1A, V _{GS} =0V
Diode forward current	I _S			-3.5	A	
Pulsed Body-Diode Current	I _{SM}			-40	A	
Input capacitance	C _{iss}		760		pF	V _{DS} =-15V, V _{GS} =0V, f=1MHz
Output capacitance	C _{oss}		140		pF	
Reverse transfer capacitance	C _{rss}		95		pF	
Gate resistance	R _g		3.2	5	Ω	V _{DS} =0V, V _{GS} =0V, f=1MHz
Total gate charge	Q _g		6.7		nC	V _{GS} =-4.5V, V _{DS} =-15V, I _D =-5.3A
Total gate charge			13.6	16	nC	V _{GS} =-10V, V _{DS} =-15V, I _D =-5.3A
Gate-source charge	Q _{gs}		2.5		nC	
Gate-drain charge	Q _{gd}		3.2		nC	
Turn-on delay time	t _{d(on)}		8		nS	V _{GS} =-10V, V _{DS} =-15V, R _{GEN} =3Ω, R _L =2.8Ω
Turn-on rise time	t _r		6		nS	
Turn-off delay time	t _{d(off)}		17		nS	
Turn-off fall time	t _f		5		nS	
Body Diode Reverse Recovery Time	t _{rr}		15		nS	I _F =-5.3A, dI/dt=100A/μs
Body Diode Reverse Recovery Charge	Q _{rr}		9.7		nC	I _F =-5.3A, dI/dt=100A/μs

*Pulse test ; Pulse width ≤300μs, Duty cycle ≤ 0.5% .

COMPLEMENTARY MOSFET

P-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

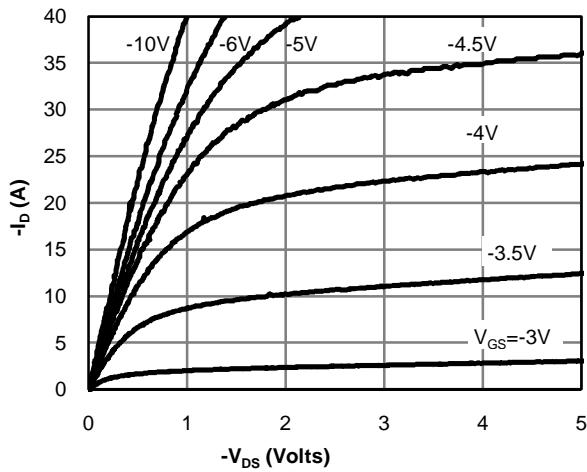


Fig 1: On-Region Characteristics

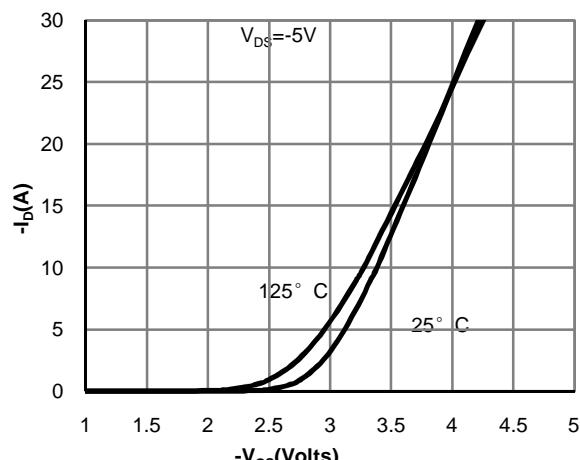


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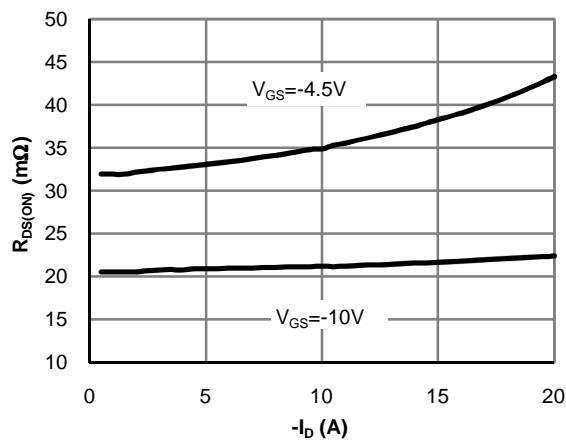


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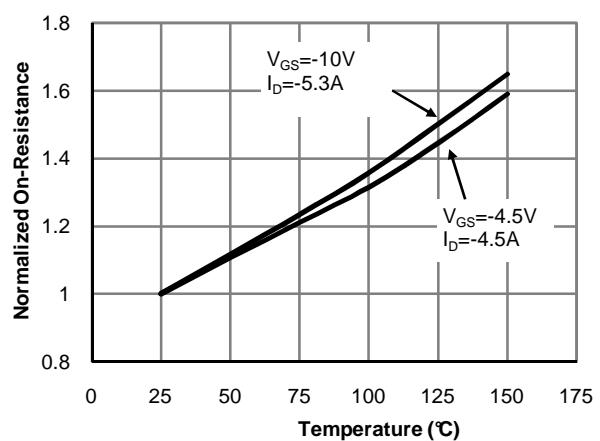


Figure 4: On-Resistance vs. Junction Temperature

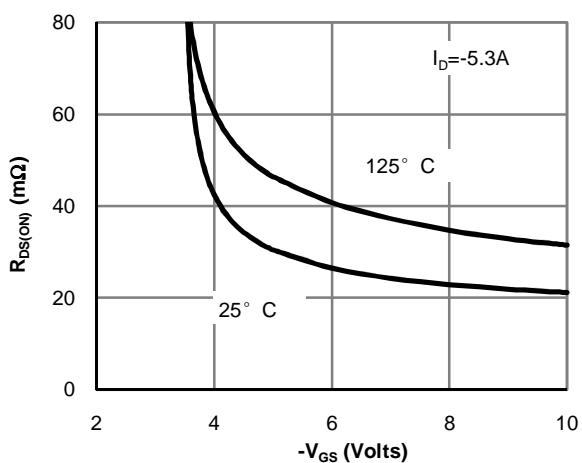


Figure 5: On-Resistance vs. Gate-Source Voltage

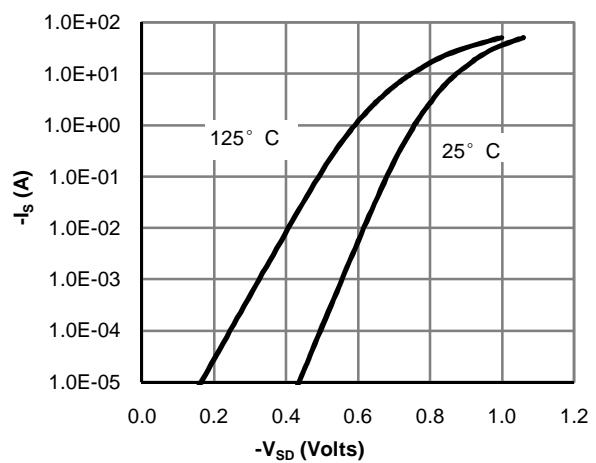


Figure 6: Body-Diode Characteristics

COMPLEMENTARY MOSFET

P-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

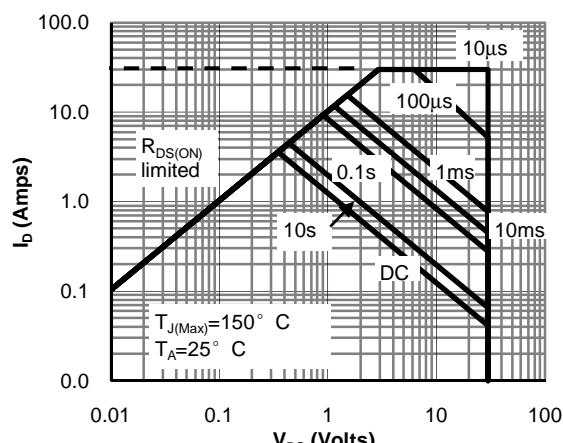
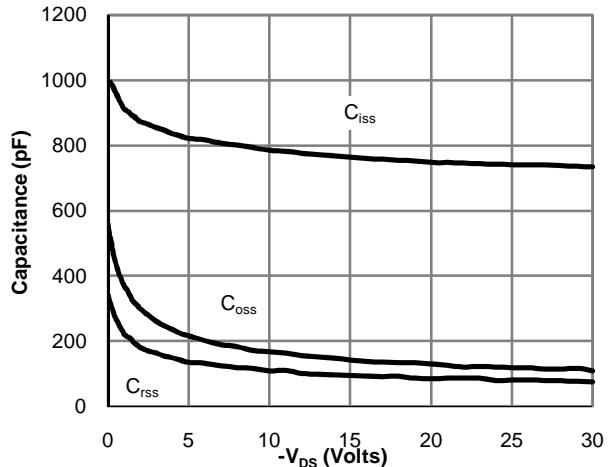
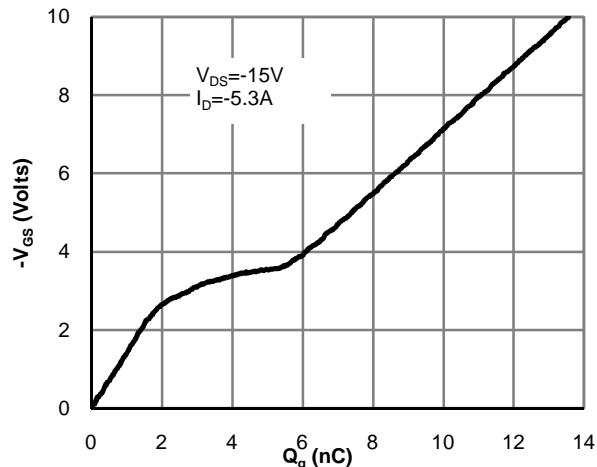


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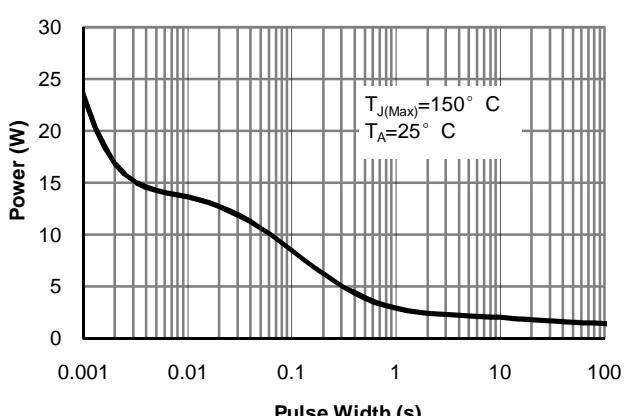


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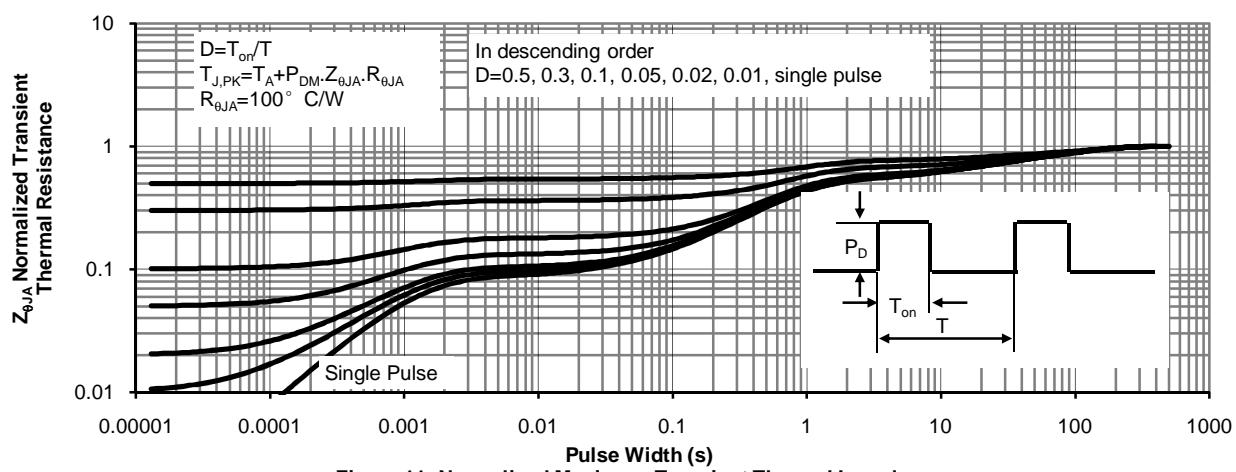
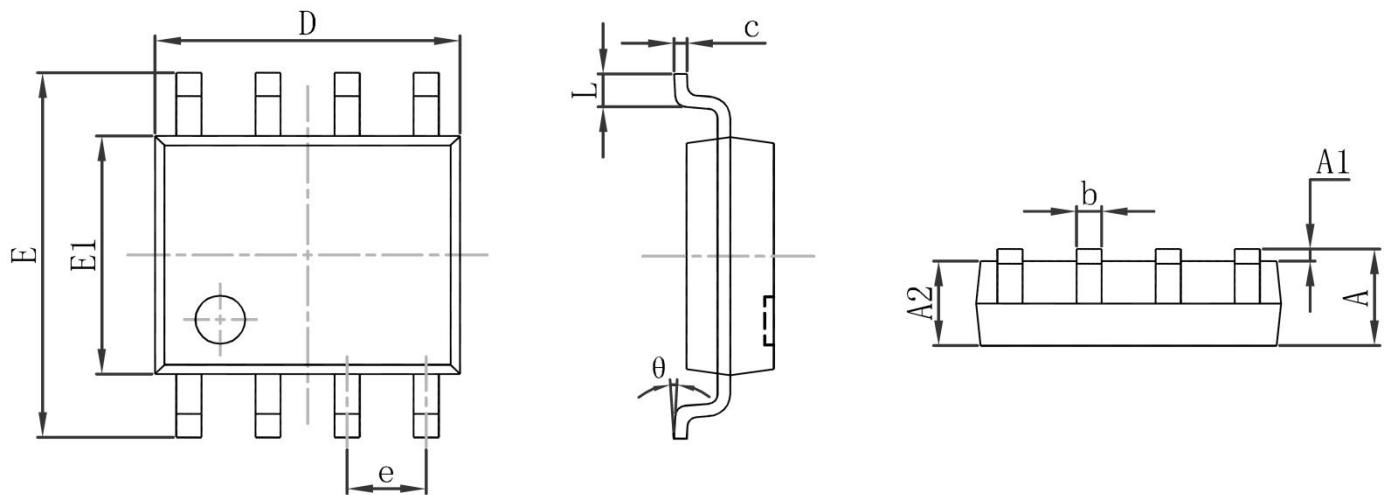


Figure 11: Normalized Maximum Transient Thermal Impedance

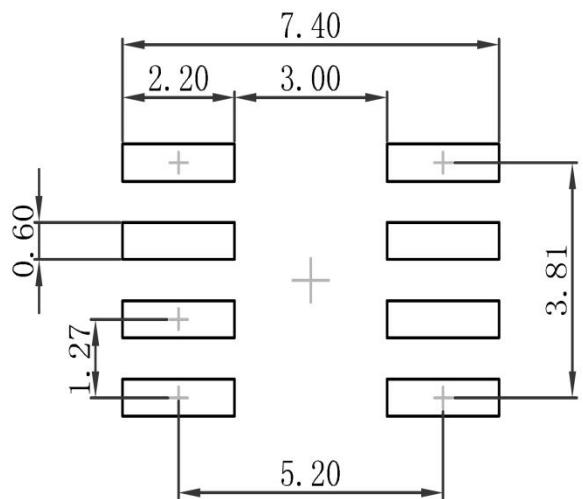
COMPLEMENTARY MOSFET

SOP-8 Package Outline Dimensions



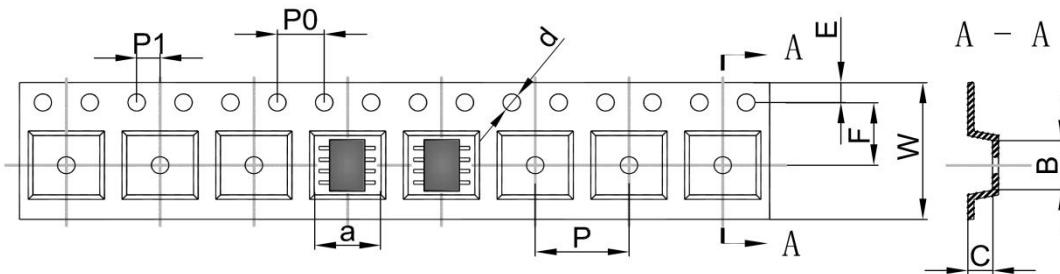
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270(BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

SOP-8 Suggested Pad Layout

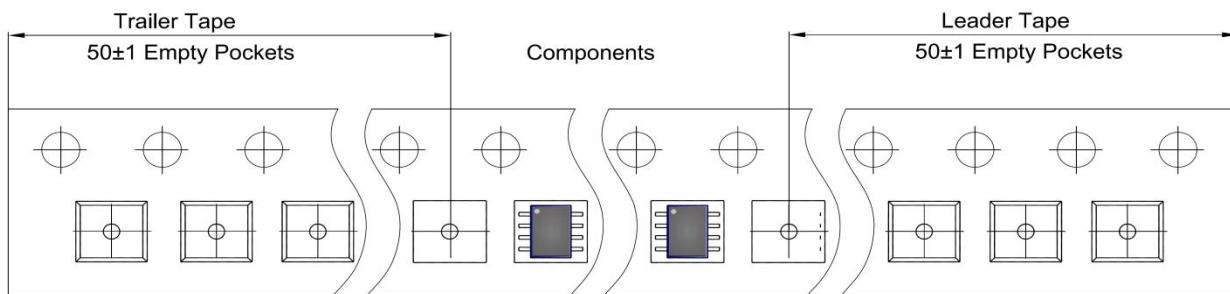
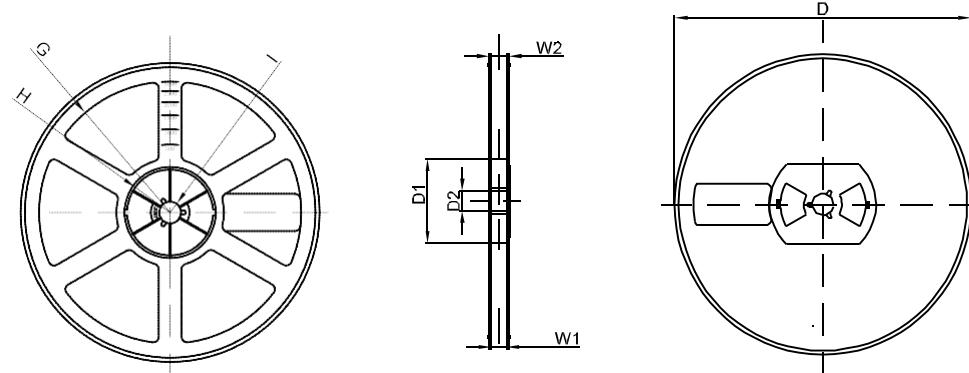


Note:

1. Controlling dimension: in millimeters
2. General tolerance: ±0.05mm
3. The pad layout is for reference purposes only

COMPLEMENTARY MOSFET
SOP-8 Tape and Reel
SOP-8 Embossed Carrier Tape


TYPE	DIMENSIONS ARE IN MILLIMETER									
	A	B	C	d	E	F	P0	P	P1	W
SOP-8	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SOP-8 Tape Leader and Trailer

SOP-8 Reel


REEL OPTION	DIMENSIONS ARE IN MILLIMETER							
	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330.00	100.00	13.00	R151.00	R56.00	R6.50	12.40	17.60
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1